



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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REVISIONS				
SYM	ECN	DESCRIPTION	DATE	APPROVED
-	----	SEE SHEET 1/2	----	---

Table 1
keys and colors

Coding A graphite black sim. RAL9011	Coding B natural sim. RAL9001	Coding C light blue sim. RAL5012	Coding D claret violet sim. RAL4004	Coding Z water blue sim. RAL5021

Notes:

1. Material and plating:

Component	Material	Plating
Housing:	PA4T, UL94-V0, color see table	
Dielectric:	LCP, UL94-V0, color black	
Outer contact (PCB):	Zinc alloy	Tin, 2-6um, over nickel
Cover:	Stainless Steel.	
HSD contact:	Copper alloy	Gold, 0.15um (interface); gold flash(PCB)
MQS contact:	Copper alloy	Tin, 2-6um, over nickel

4. Environmental data:

Temperature range	-40°C to +105°C
Thermal shock	DIN IEC 60068-2-14 Test Na
Temperature and humidity	USCar 2 - 4 5.6.2
Vibration (Random)	DIN IEC 60068-2-64
Mechanical Shock	DIN IEC 60068-2-27
High-Temp. Exposure	DIN IEC 60068-2-2
Soldering profile	acc. to IEC 60068-2-58; Group 3&4
2011/65/EU (RoHS)	compliant

2. Electrical data, HSD side:

Impedance, even mode	≈ 32 Ω common mode only
Impedance, differential mode	100 Ω differential signaling, for one pair or quad cable shielded
Frequency	DC to 2.0 GHz
Return loss	≥ 20 dB to 1.0 GHz
	≥ 17 dB to 2.0 GHz
Insertion loss	≤ 0.1 dB @ 1.0 GHz
Skew (between signal contacts)	≤ 20 psec. (can be reduced by layout)
Nearend-Crosstalk	≤ 30 dB
Farend-Crosstalk	≤ 35 dB
Insulation resistance	≥ 1x10 ³ MΩ
Signal contact resistance	≤ 10 mΩ
Outer contact resistance	≤ 7.5 mΩ
Test voltage	500 V rms
Working voltage	100 V rms
Test current capability at 80°C	≤ 1.5 A DC
Test current capability at 80°C MQS pins	≤ 5.0 A DC (dependent on mating connector and cable)

5. Packing

Standard	100 pcs in tape & reel
Weight	12.97 g/pc

6. Order P/N system:

HSD NXRP PCB 8X
 Coding: _____ Packing method:
 See table 1 A- Packing by tape & reel
 B- Packing by tray
 C- Single Packing

3. Mechanical data, HSD side:

Mating cycles	≥ 25
Engagement force each contact	≤ 30 N
Disengagement force each contact	≥ 5 N
Retention force latch	≥ 110 N
Coding efficiency	≥ 80 N

UNLESS OTHERWISE SPECIFIED TOLERANCES U.S. METRIC .X +/- 0.50 .XX +/- 0.25 .XXX +/- 0.10 FRACTIONS +/- 1/16 ANGLES +/- 5° FOR MATERIALS AND FINISHES SEE NOTES REMOVE SHARP EDGES DIMENSIONS U.S. INCHES METRIC MM	APPROVAL DRAWN Kaka Yang CHECKED [Signature] CHECKED [Signature]	DATE 11/21/16 11/21/16	Amphenol TITLE HSD + 8pos MQS R/A plug connector NORTH LOCATION SIZE DRAWING NO. A4 HSD NXRP PCB 8X SCALE 2:1 SHEET 2 OF 2
	ANGLE OF PROJECTION [Diagram]	DRAWING FILE: [Blank]	